Special Issue

Artificial Intelligence on the Edge for Industry 4.0

Message from the Guest Editors

This special issue is based on the conference "Industry 4.0 and Beyond - The Final Conference of the PLANET4 Project", which is planned for the 2nd October in Pisa, Italy, as the final event of the PLANET4 project. It will provide an excellent international forum for disseminating original research results, new ideas and practical development experiences concentrating on both the theory and practices of academics, researchers, engineers and industry professionals. It aims to bring together researchers and scientists from academia, industry and research centers to present the results of ongoing research, exchange ideas and identify future research directions in the following areas: Industry 4.0; data science, artificial intelligence and machine learning; internet of things and industrial internet of things; and cloud and edge computing.

Guest Editors

Prof. Dr. Chrysostomos Stylios

Dr. Dorota Stadnicka

Dr. Joan Navarro

Dr. Daniele Mazzei

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multidimensional network.

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo

Dipartimento di Fisica, Politecnico di Milano, Piazza L. da Vinci 32, 20133 Milano, Italy

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